Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J–Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Low Forward Voltage Drop
- Pb-Free Package is Available

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Average Rectified Forward Current (At Rated V _R , T _C = 110°C)	Io	1.0	Α
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 100 kHz, T _C = 110°C)	I _{FRM}	2.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	40	Α
Storage / Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C
Operating Junction Temperature	T _J	-55 to +125	°C
Voltage Rate of Change (Rated V_R , $T_J = 25^{\circ}C$)	dv/dt	10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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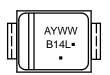
http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 1.0 AMPERE – 40 VOLTS



SMB CASE 403A PLASTIC

MARKING DIAGRAM



B14L = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRS140LT3	SMB	2500/Tape & Reel
MBRS140LT3G	SMB (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

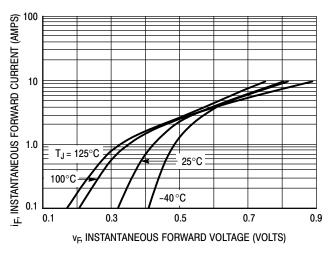
Characteristic		Max	Unit
Thermal Resistance, Junction-to-Lead (Note 1)		24	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	80	°C/W

ELECTRICAL CHARACTERISTICS

Characteristic		Symbol	T _J = 25°C	T _J = 125°C	Unit
Maximum Instantaneous Forward Voltage (Note 3)	(i 10A)	٧ _F	0.5 0.6	0.425 0.58	V
see Figure 2	$(i_F = 1.0 A)$ $(i_F = 2.0 A)$		0.0	0.50	
Maximum lastantagasus Rayana Cumant (Nata 2)			T _J = 25°C	T _J = 100°C	
Maximum Instantaneous Reverse Current (Note 3)	$(V_R = 40 \text{ V})$	I _R	0.4	10	mA
see Figure 4	$(V_R = 20 \text{ V})$		0.02	5.0	

^{3.} Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2.0%.

Mounted with minimum recommended pad size, PC Board FR4.
 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.



1.0 T_J = 125°C 100°C 1.0 0.1 0.3 0.5 0.7 0.9 V_F, MAXIMUM INSTANTANEOUS FORWARD VOLTAGE (VOLTS)

Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

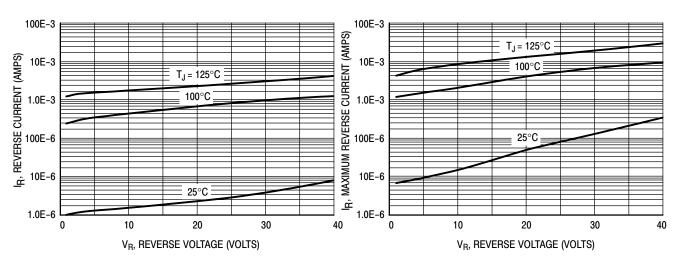
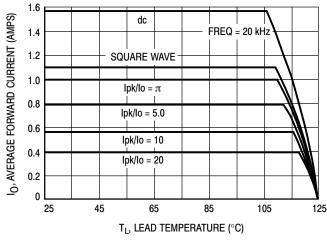


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current



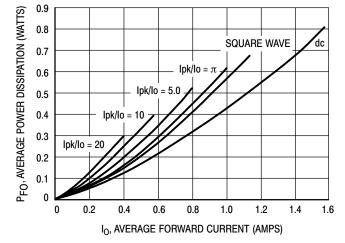


Figure 5. Current Derating

Figure 6. Forward Power Dissipation

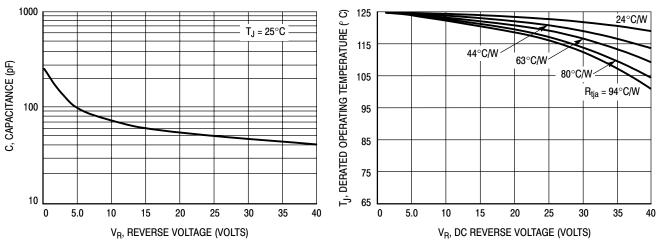


Figure 7. Capacitance

Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where

r(t) = thermal impedance under given conditions,

Pf = forward power dissipation, and

Pr = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

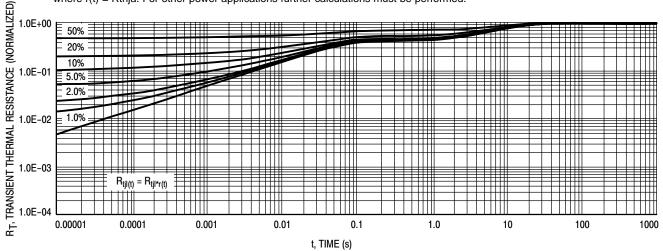


Figure 9. Thermal Response, Junction-to-Lead

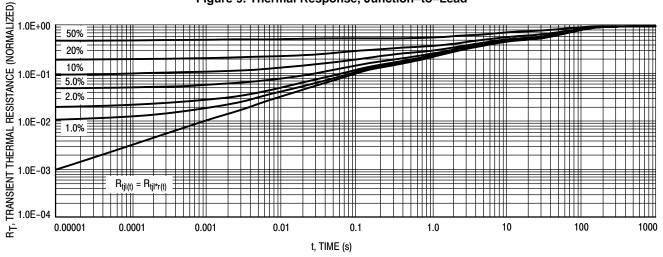
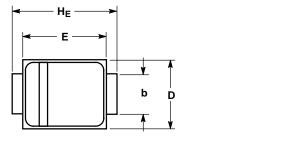
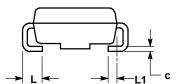


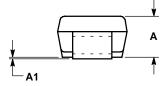
Figure 10. Thermal Response, Junction-to-Ambient

PACKAGE DIMENSIONS

SMB PLASTIC PACKAGE CASE 403A-03 ISSUE F





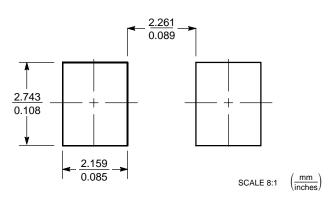


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	MILLIMETERS		INCHES			
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α	1.90	2.13	2.45	0.075	0.084	0.096
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1		0.51 REF		0.020 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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